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(12) **United States Design Patent**  
**Chen et al.**

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(54) **LIGHT EMITTING DIODE**

(71) Applicant: **EVERLIGHT ELECTRONICS CO., LTD.**, New Taipei (TW)

(72) Inventors: **Yung-Chieh Chen**, New Taipei (TW);  
**Jung-Chiuan Lin**, New Taipei (TW)

(73) Assignee: **EVERLIGHT ELECTRONICS CO., LTD.**, New Taipei (TW)

(\*\*) Term: **15 Years**

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**Related U.S. Application Data**

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(30) **Foreign Application Priority Data**

Jun. 17, 2016 (TW) ..... 105303468

(51) **LOC (12) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/180**

(58) **Field of Classification Search**  
USPC ..... D13/180; D26/1

(Continued)

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*Primary Examiner* — Selina Sikder

(74) *Attorney, Agent, or Firm* — Sughrue Mion, PLLC

(57) **CLAIM**

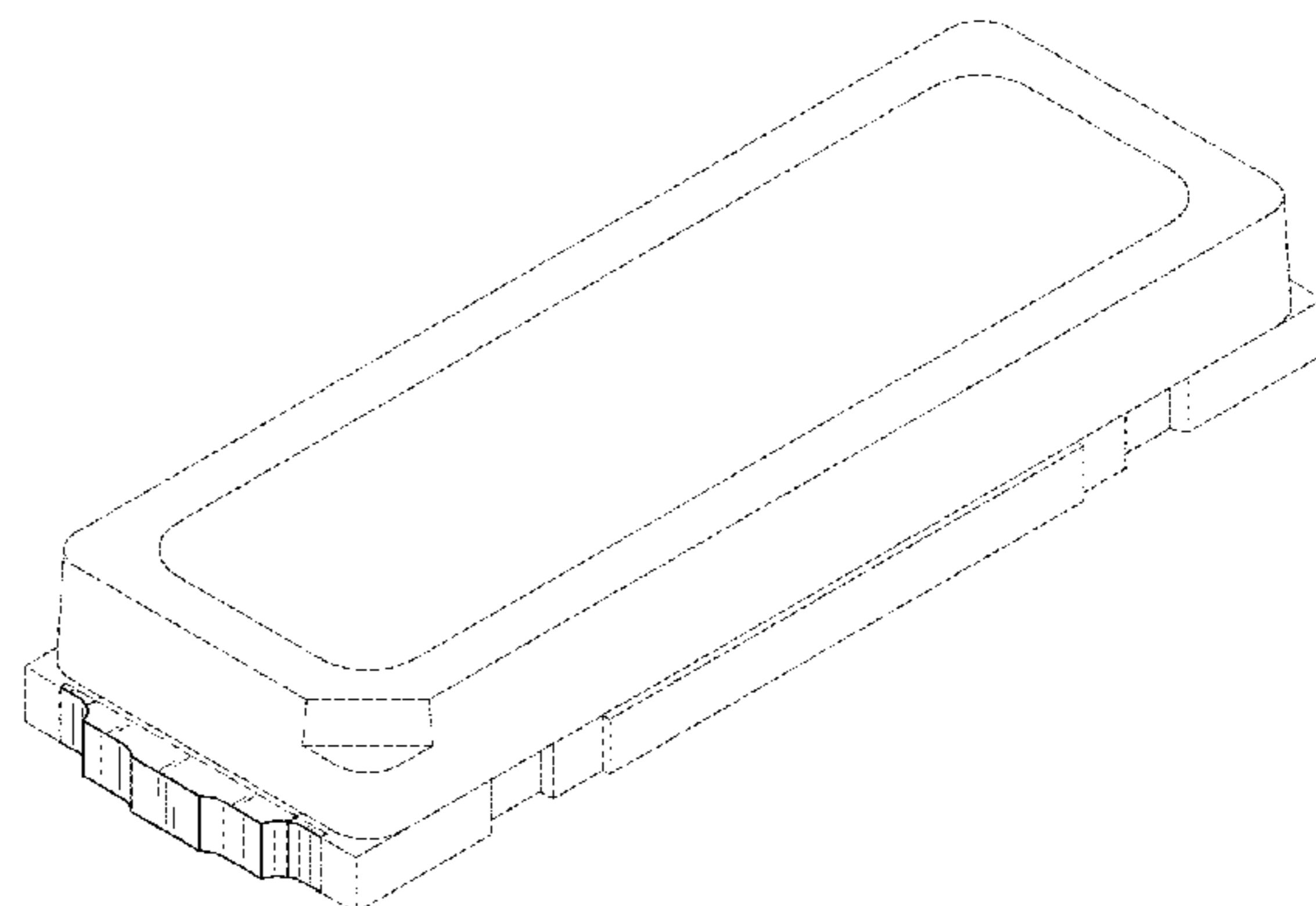
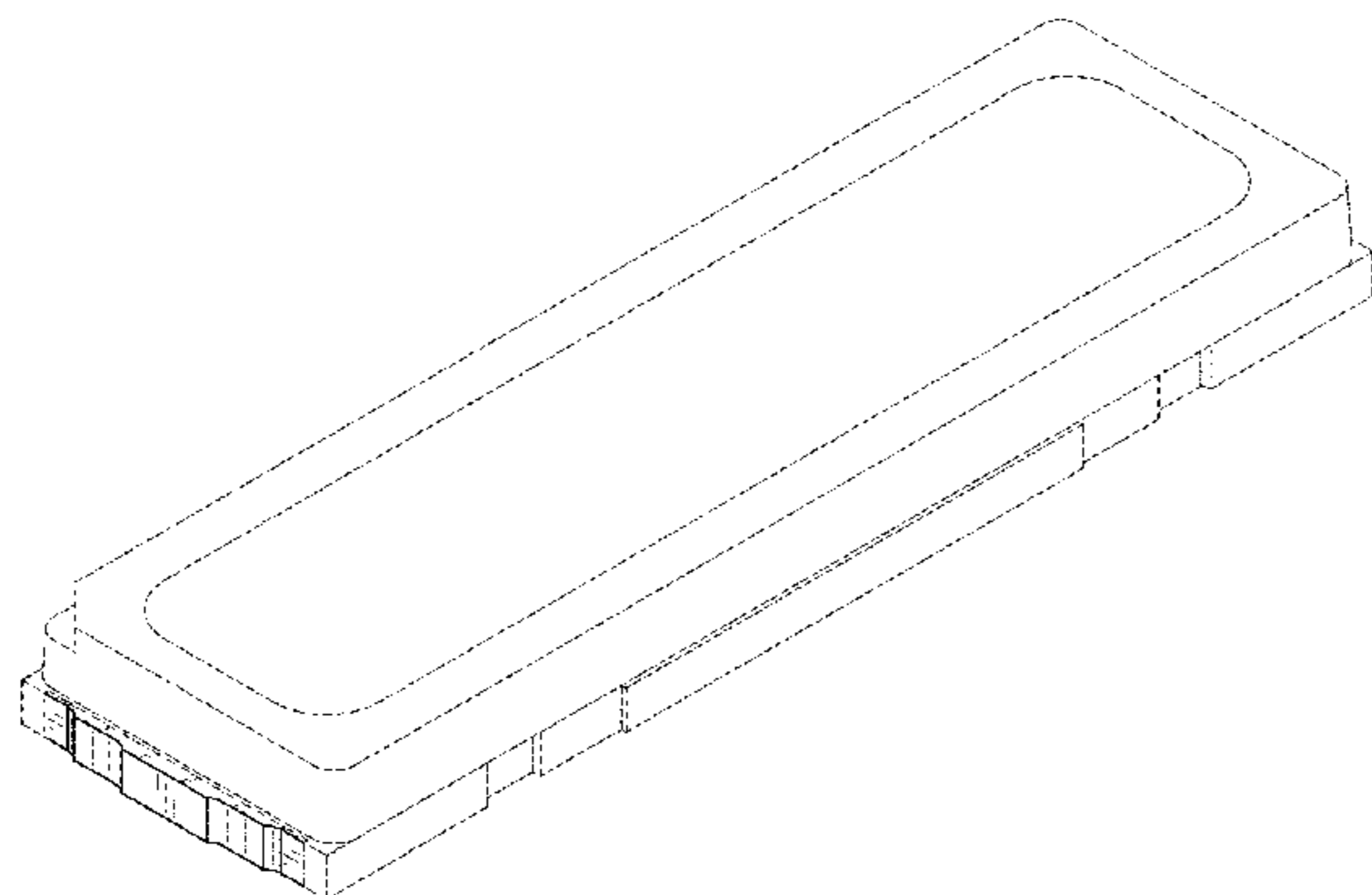
The ornamental design for a light emitting diode, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a light emitting diode showing a first embodiment of our new design; FIG. 2 is another perspective view of the first embodiment; FIG. 3 is a front view of the first embodiment; FIG. 4 is a rear view of the first embodiment; FIG. 5 is a left side view of the first embodiment; FIG. 6 is a right side view of the first embodiment; FIG. 7 is a top view of the first embodiment; FIG. 8 is a bottom view of the first embodiment; FIG. 9 is a perspective view of a light emitting diode showing a second embodiment of our new design; FIG. 10 is another perspective view of the second embodiment; FIG. 11 is a front view of the second embodiment; FIG. 12 is a rear view of the second embodiment; FIG. 13 is a left side view of the second embodiment; FIG. 14 is a right side view of the second embodiment; FIG. 15 is a top view of the second embodiment; and, FIG. 16 is a bottom view of the second embodiment.

The dashed line portions in the drawings form no part of the claimed design. The dot-dash lines in the drawings define the bounds of the claimed design and form no part thereof.

**1 Claim, 10 Drawing Sheets**



(58) **Field of Classification Search**

CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;  
 H01L 27/156; H01L 31/02; H01L 33/00;  
 H01L 33/04; H01L 33/08; H01L 33/10;  
 H01L 33/20; H01L 33/38; H01L 33/42;  
 H01L 33/48; H01L 33/483; H01L 33/486

See application file for complete search history.

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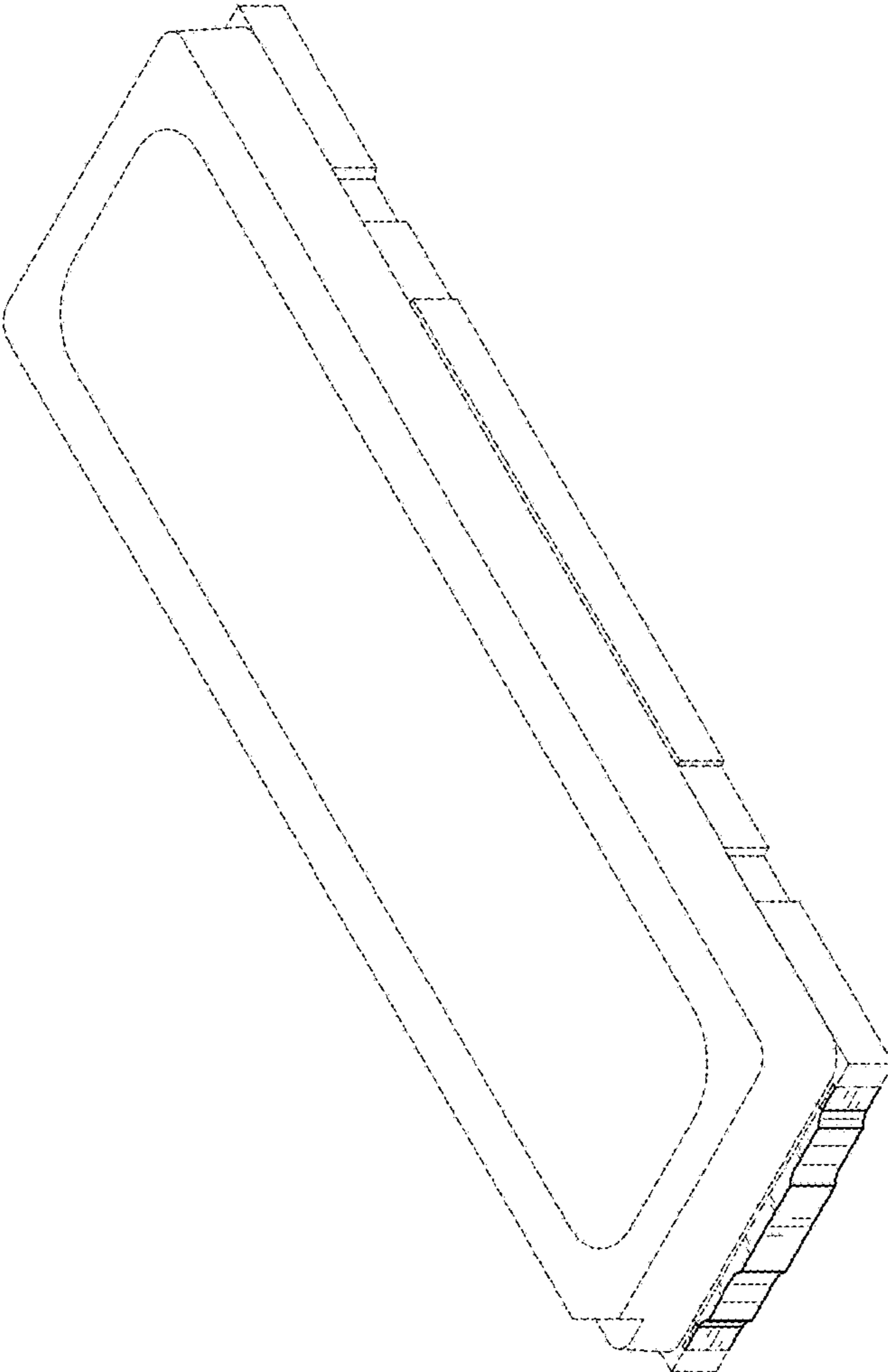


FIG. 1

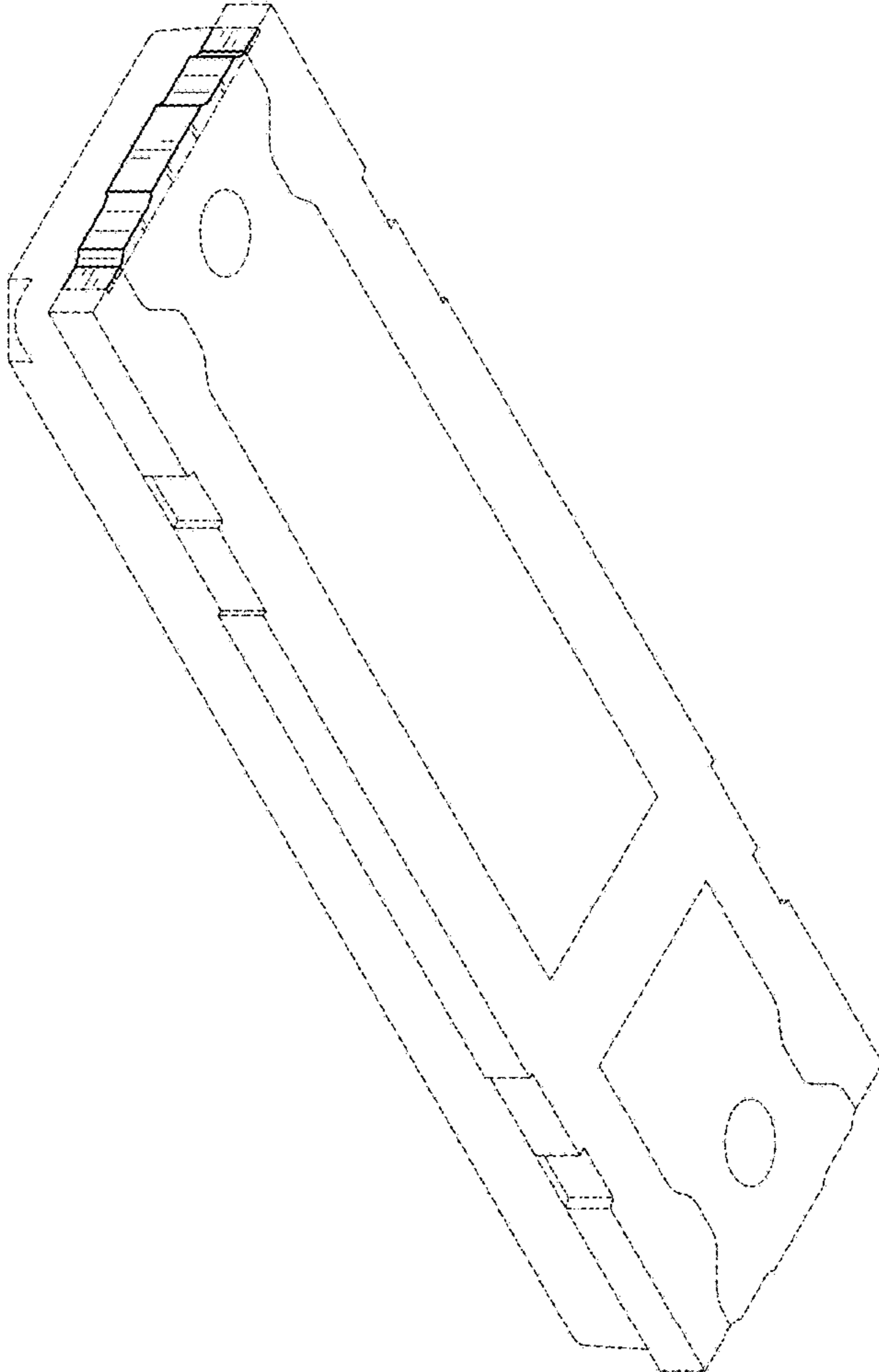


FIG. 2

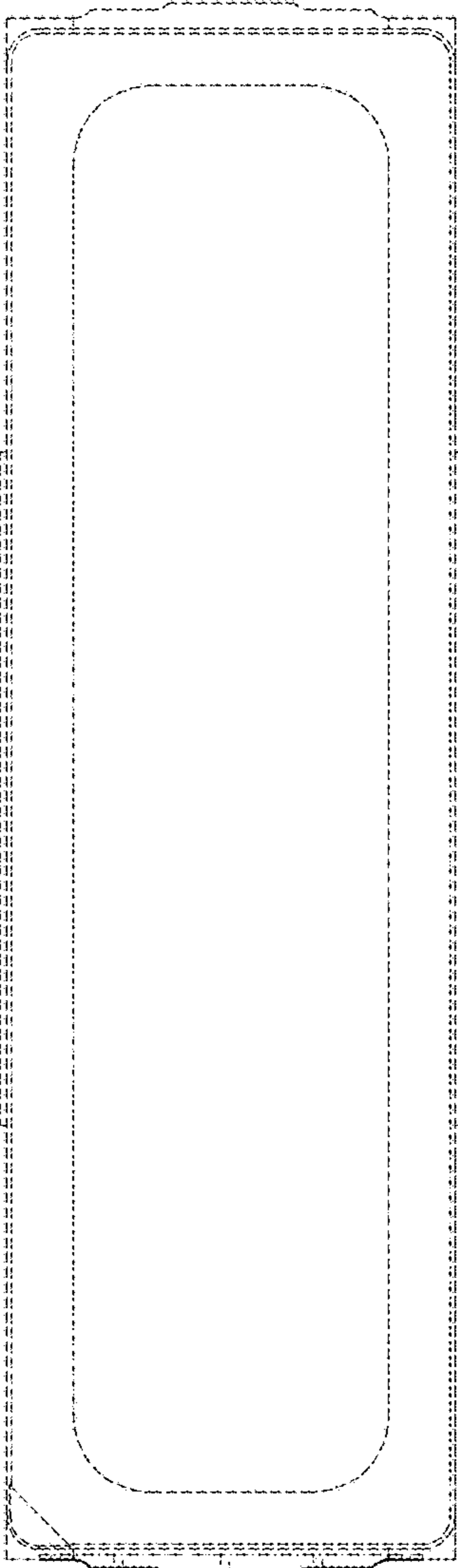


FIG. 3

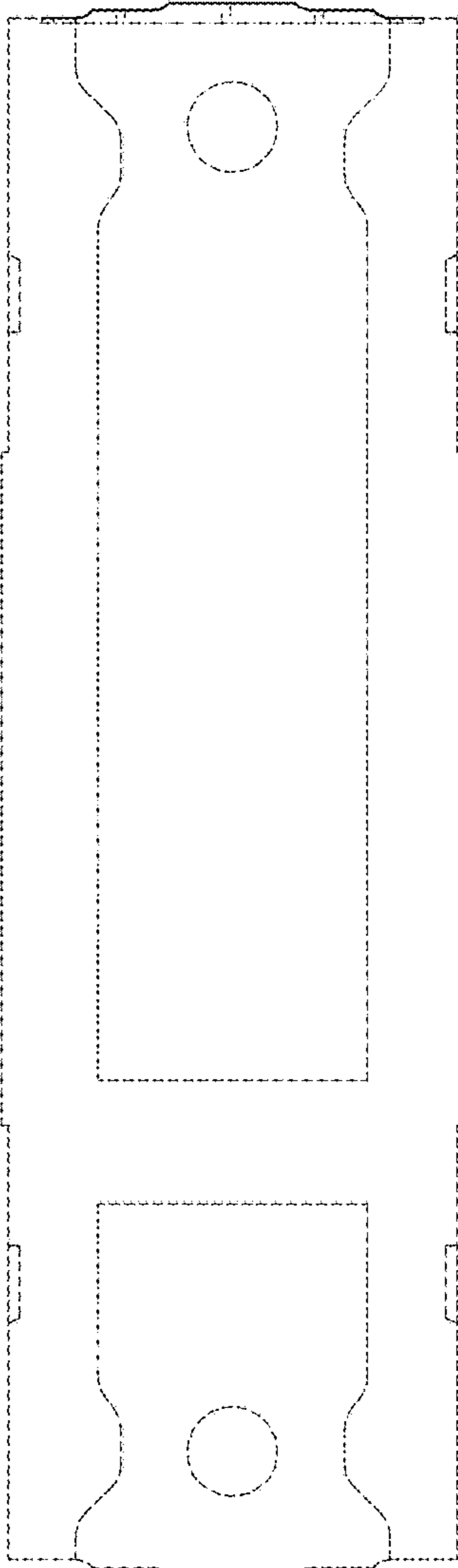


FIG. 4

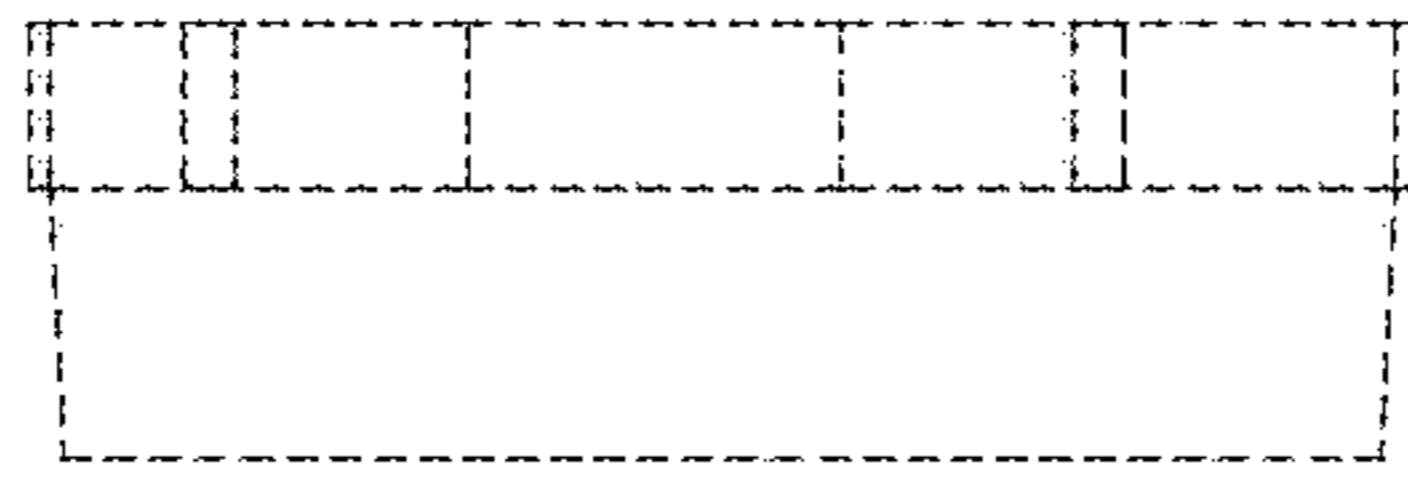


FIG. 6

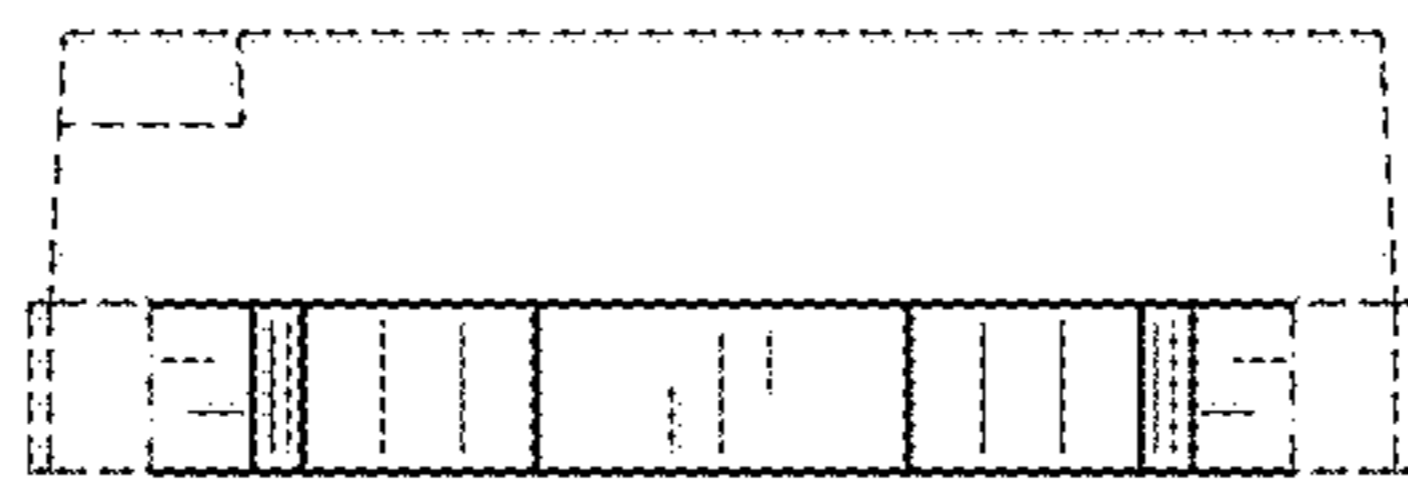


FIG. 5

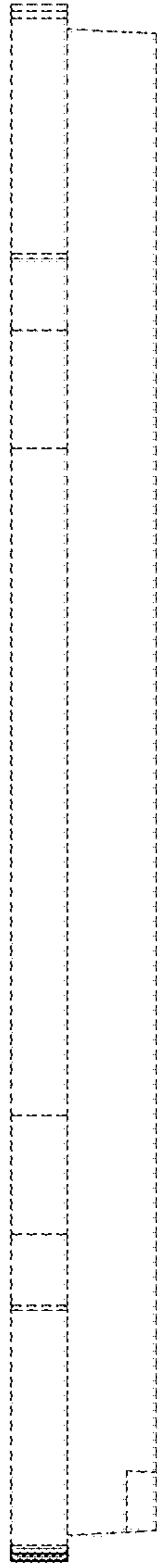


FIG. 7

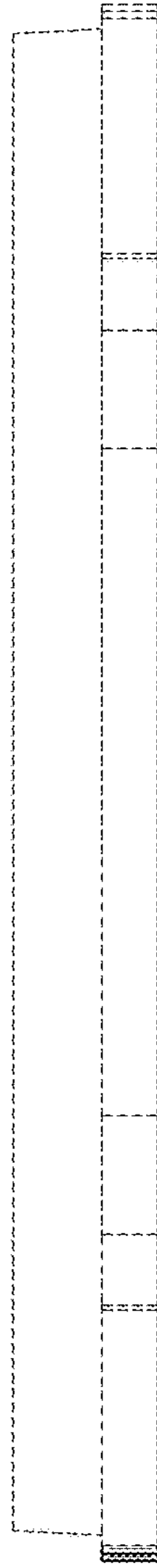


FIG. 8

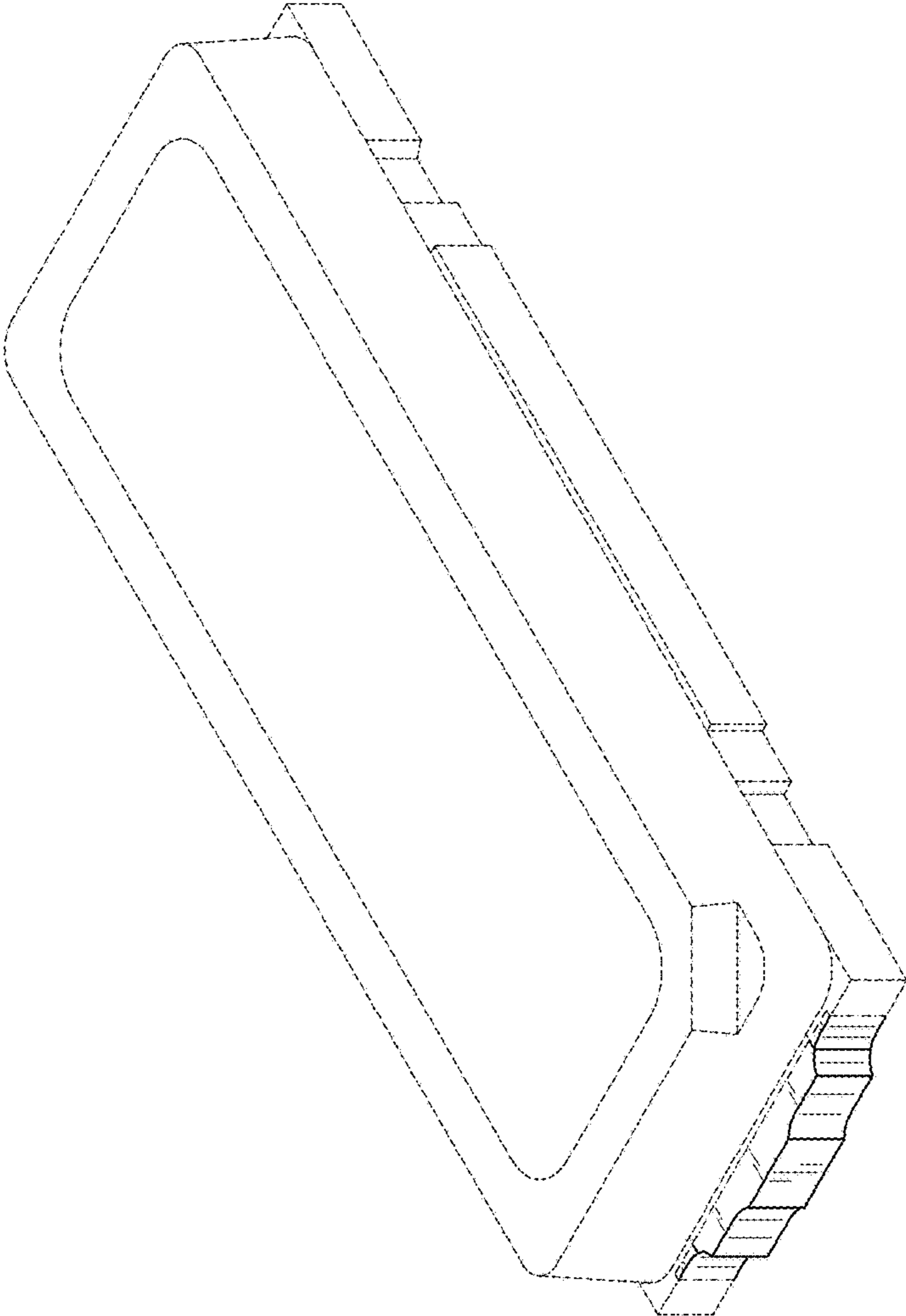


FIG. 9



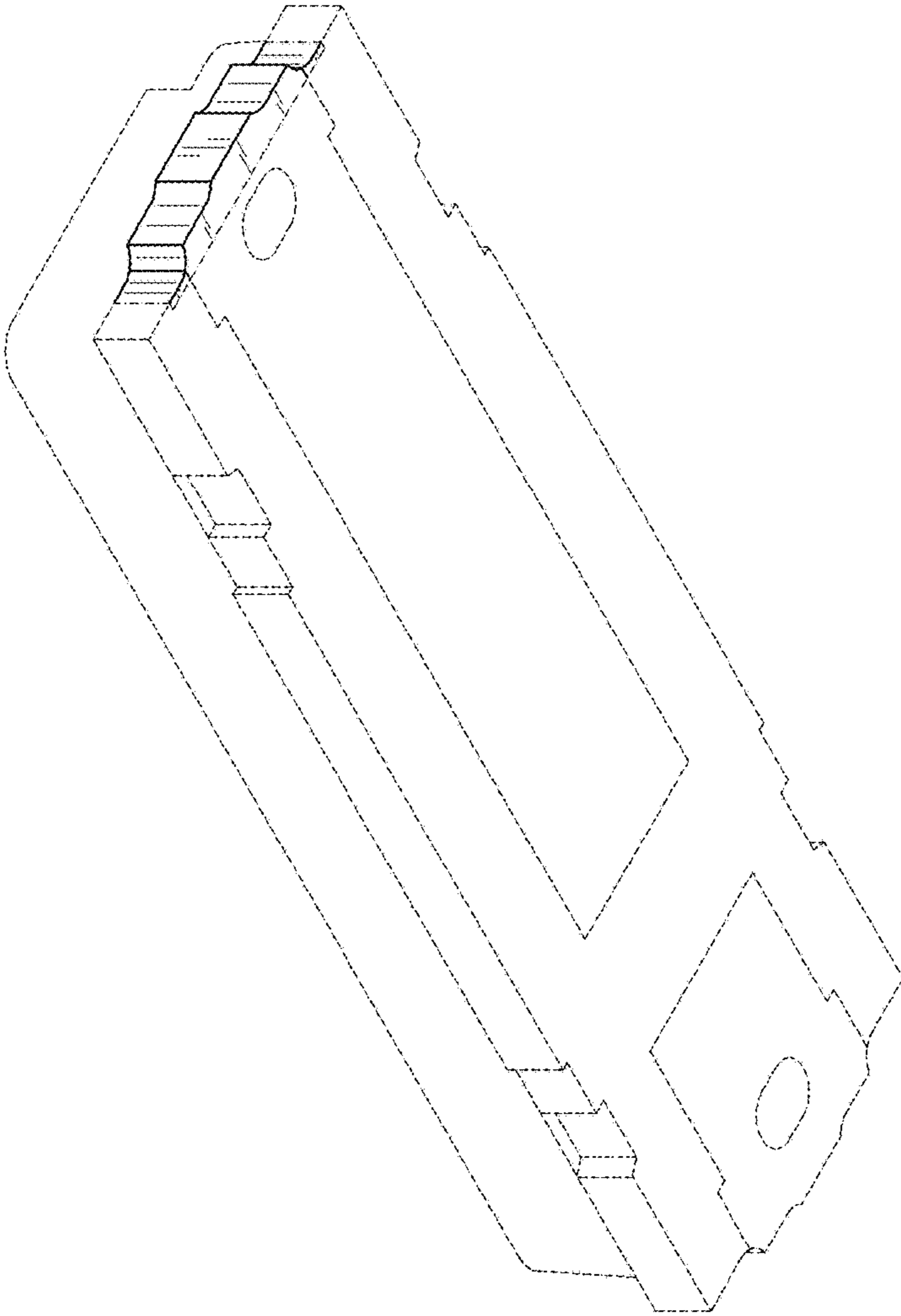


FIG. 10

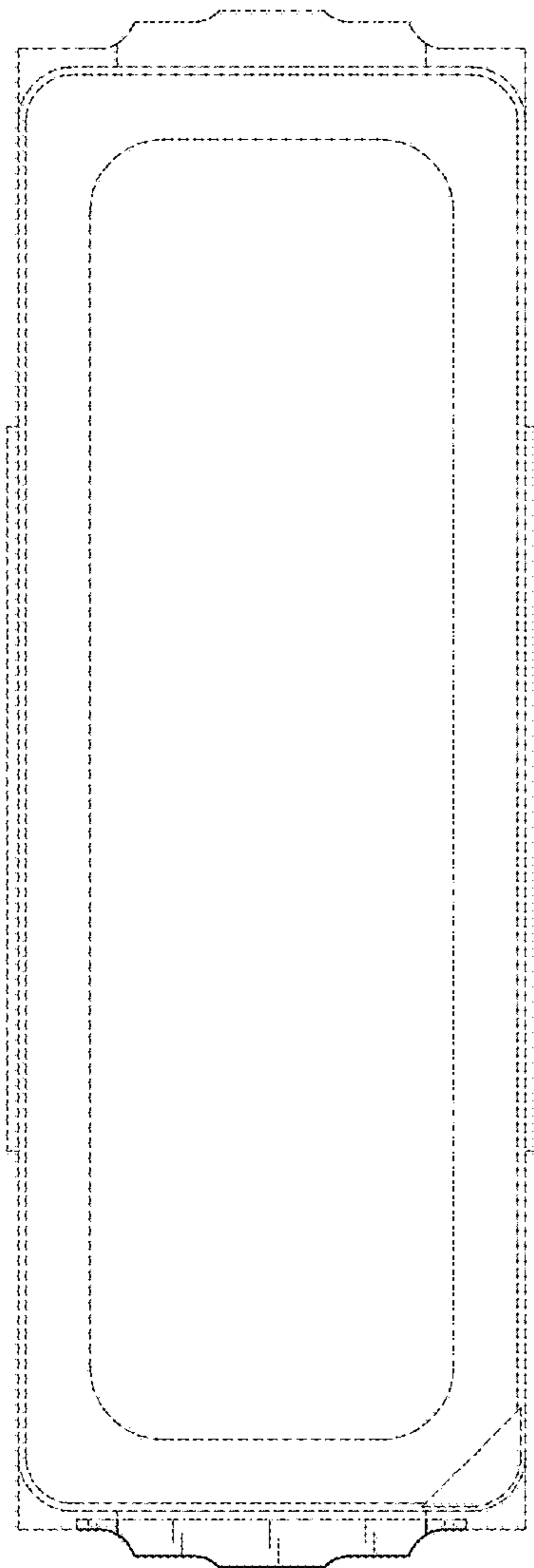


FIG. 11

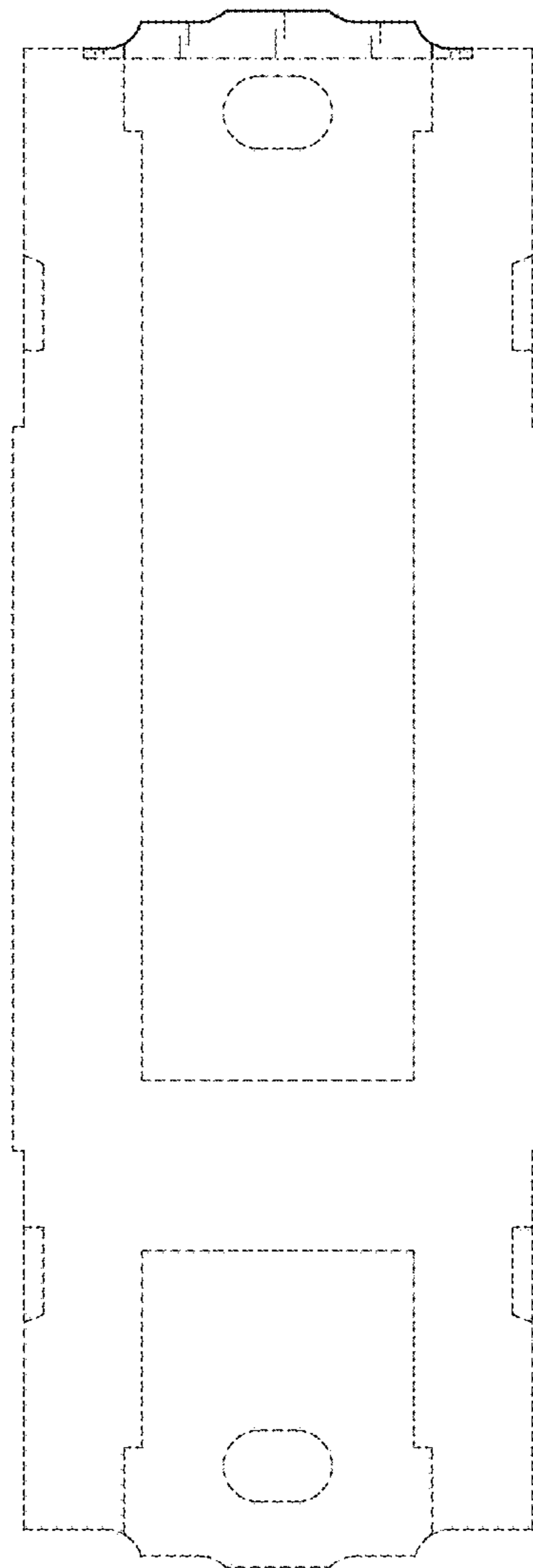


FIG. 12

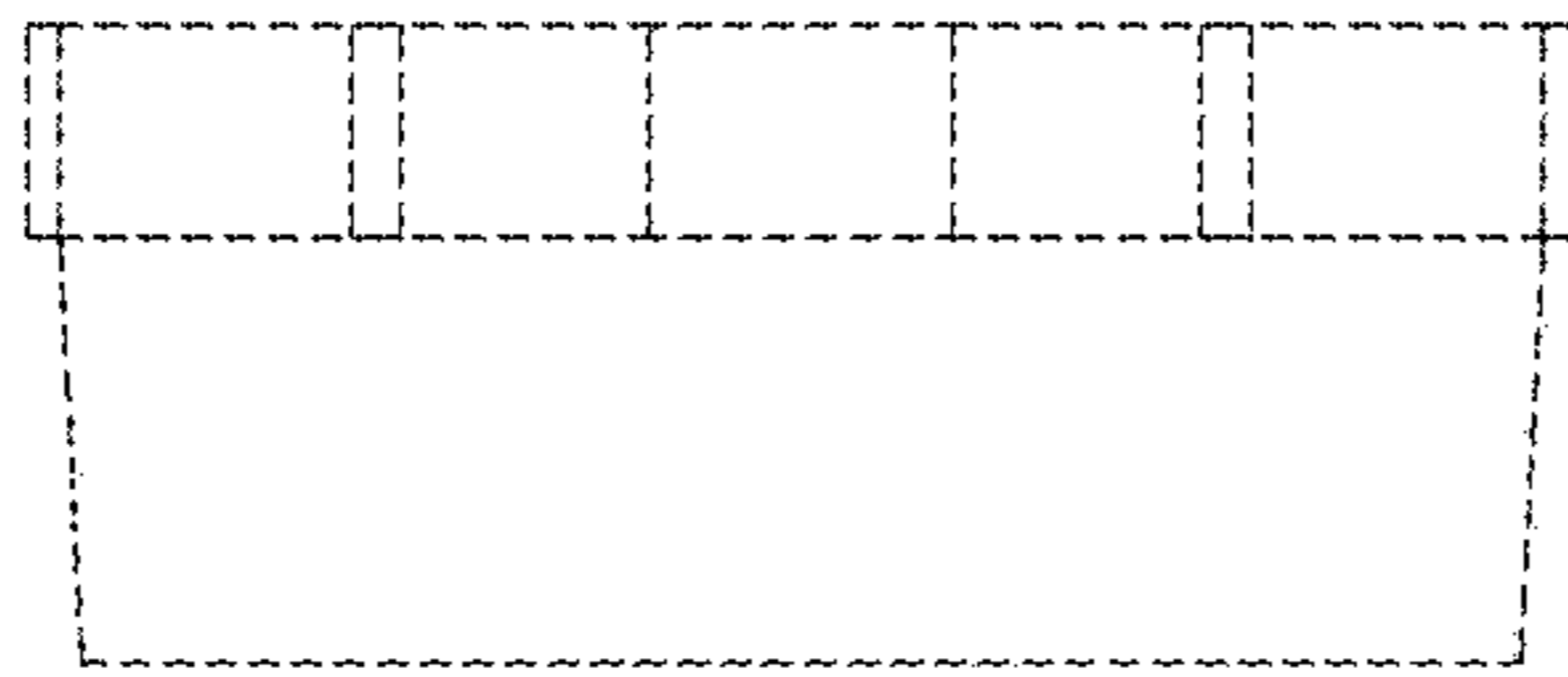


FIG. 14

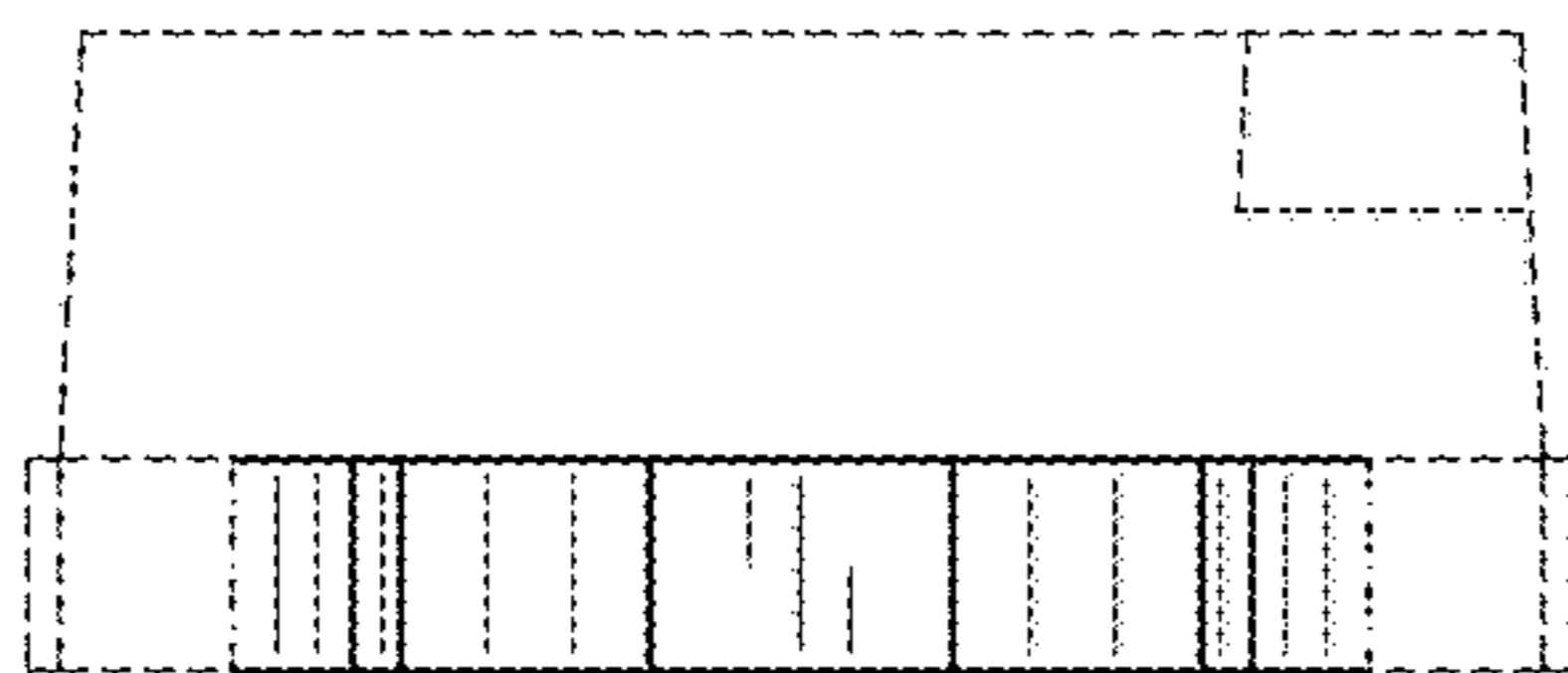


FIG. 13

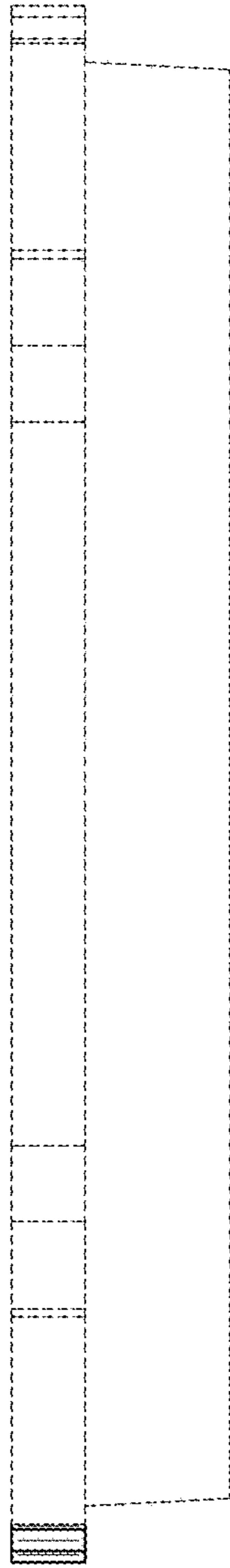


FIG. 15

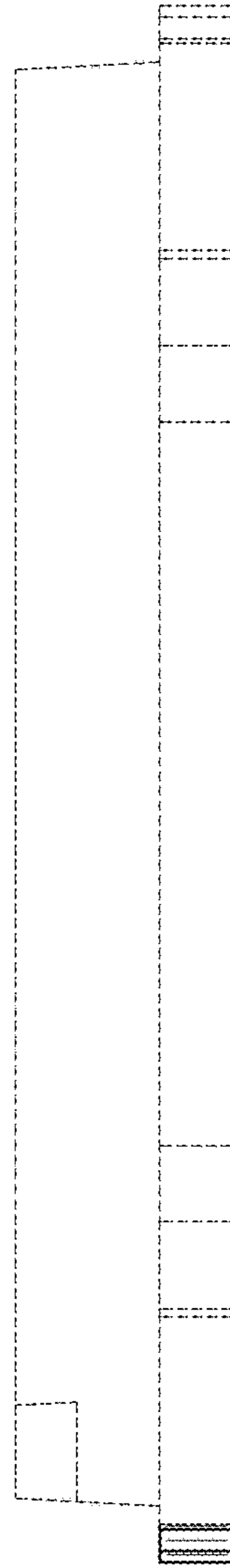


FIG. 16